



## **PROCESS CHANGE NOTICE PCN0116**

### **FineLine BGA Assembly Plant Addition**

#### **Change Description:**

Amkor, Korea will be added as a second source for FineLine BGA™ packages currently assembled in ASAT, Hong Kong. This change will not affect moisture rating, nor will there be any changes to the existing package dimension specifications. However, the molding compound used at Amkor will be Nitto HC100 (compared to Shin Etsu at ASAT).

#### **Reason For Change:**

This change will improve the FineLine BGA package assembly flexibility by providing a second sourcing option.

#### **Products Affected:**

Initial products affected will include:

EPF10K100E 484-Ball FineLine BGA  
EPF10K130E 484-Ball FineLine BGA

EPF10K200S 672-Ball FineLine BGA  
EPF10K200E 672-Ball FineLine BGA

Additional products may be affected in the future. Products assembled in the ASAT FineLine BGA package include the FLEX® and ACEX™ families.

#### **Product Traceability and Transition Dates:**

Devices assembled by Amkor in Korea will begin shipping on or after January 7, 2002 and can be distinguished by the country of origin, “Korea”, marked on the top side of the device.

#### **Contact:**

Qualification reports are available upon request. For additional information regarding the changes described in this document, please contact the Altera Customer Quality Engineering Department at (408) 544-6933.